



淺談機櫃系統散熱設計 FloTHERM in Rack

Cloud Data Center

AIC

Thermal and Acoustic Solution Design Section

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2016/11/11



AIC Introduction



2015



2016



AIC



Mark Zuckerberg



圖片來源：<http://jjj1110.pixnet.net/blog/post/66598007>

CN 中央通訊社 THE CENTRAL NEWS AGENCY 中央社 - 2012年5月8日 下午10:30

Steve Jobs

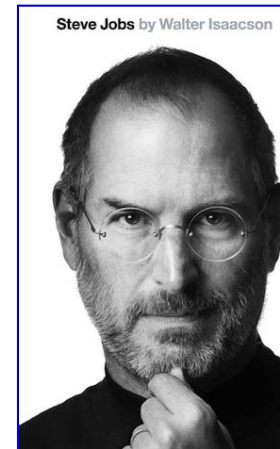
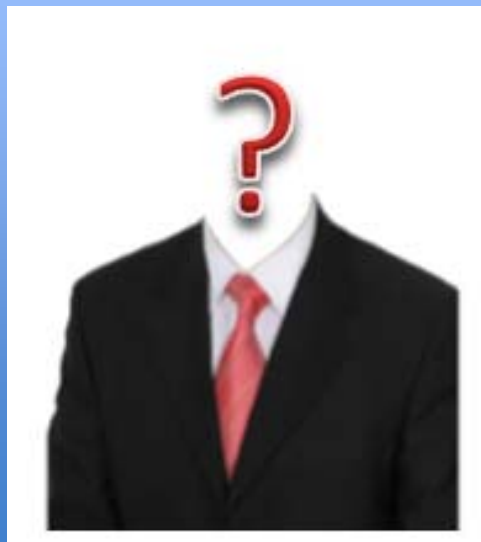


Photo from the Wikipedia of Steve Jobs

<https://zh.wikipedia.org/wiki/%E5%8F%B2%E8%92%82%E5%A4%AB%C2%B7%E4%B9%94%E5%B8%83%E6%96%AF%E4%BC%A0>

AIC New Client Mr. Mystery



The New Request from Mr. Mystery

1. Whole **Rack** level system.
2. The total height is about **48U (2300mm)**.
3. The width is smaller than **800mm** .
4. Each half rack has 21U **Sever** or **JBOD**.
5. Two kinds of **Sever U**.
6. Ambient temperature **35C**.
7. **95W / 105W / 135W CPU**



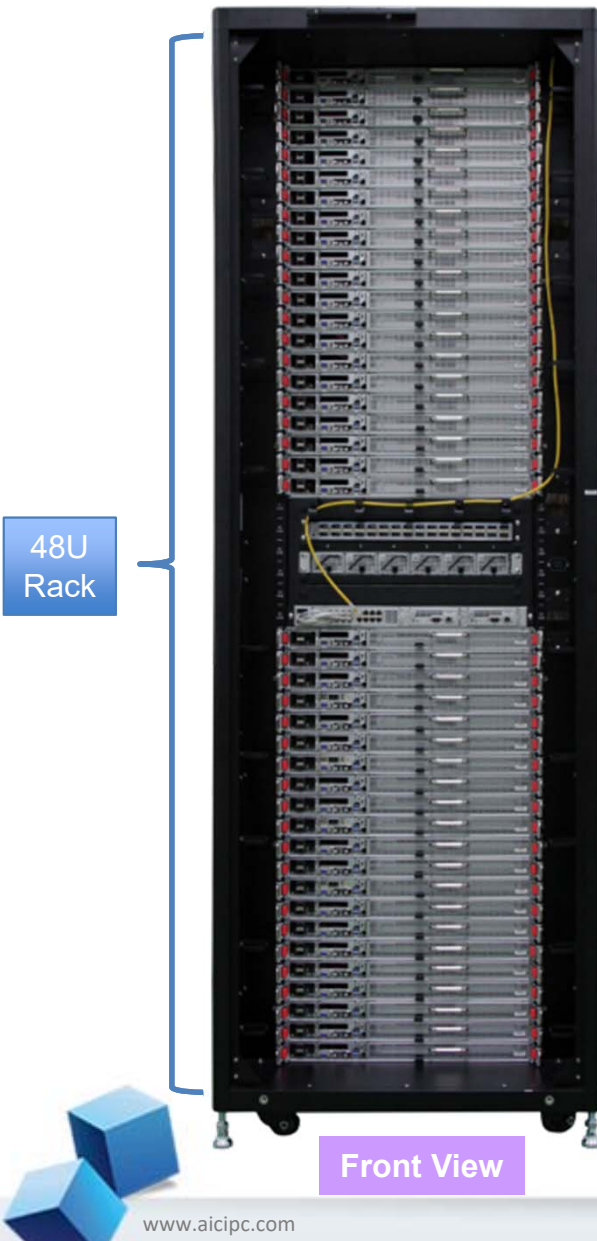
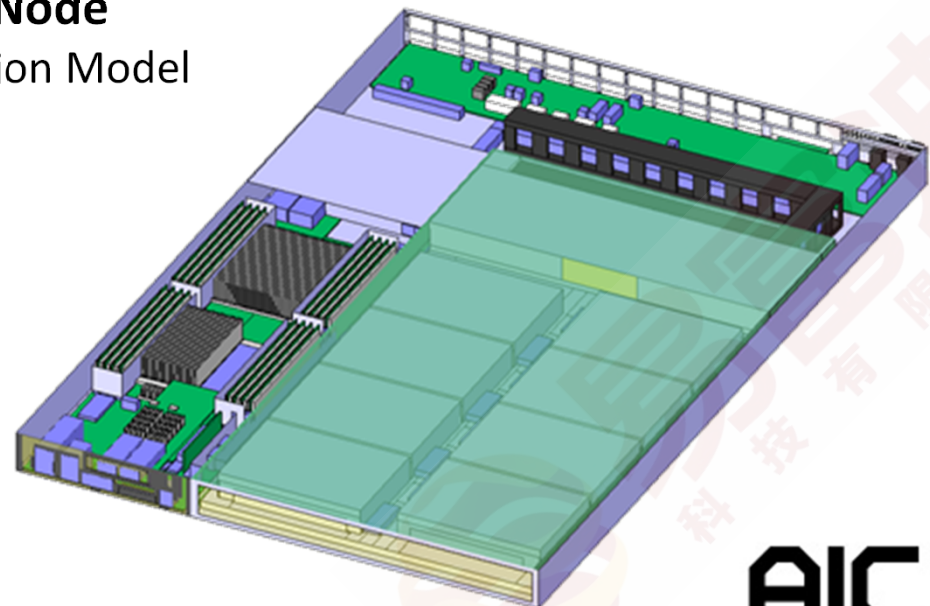
AIC Rack Thermal Simulation

Apply the Single Node into Rack

Single Node



Single Node
Simulation Model



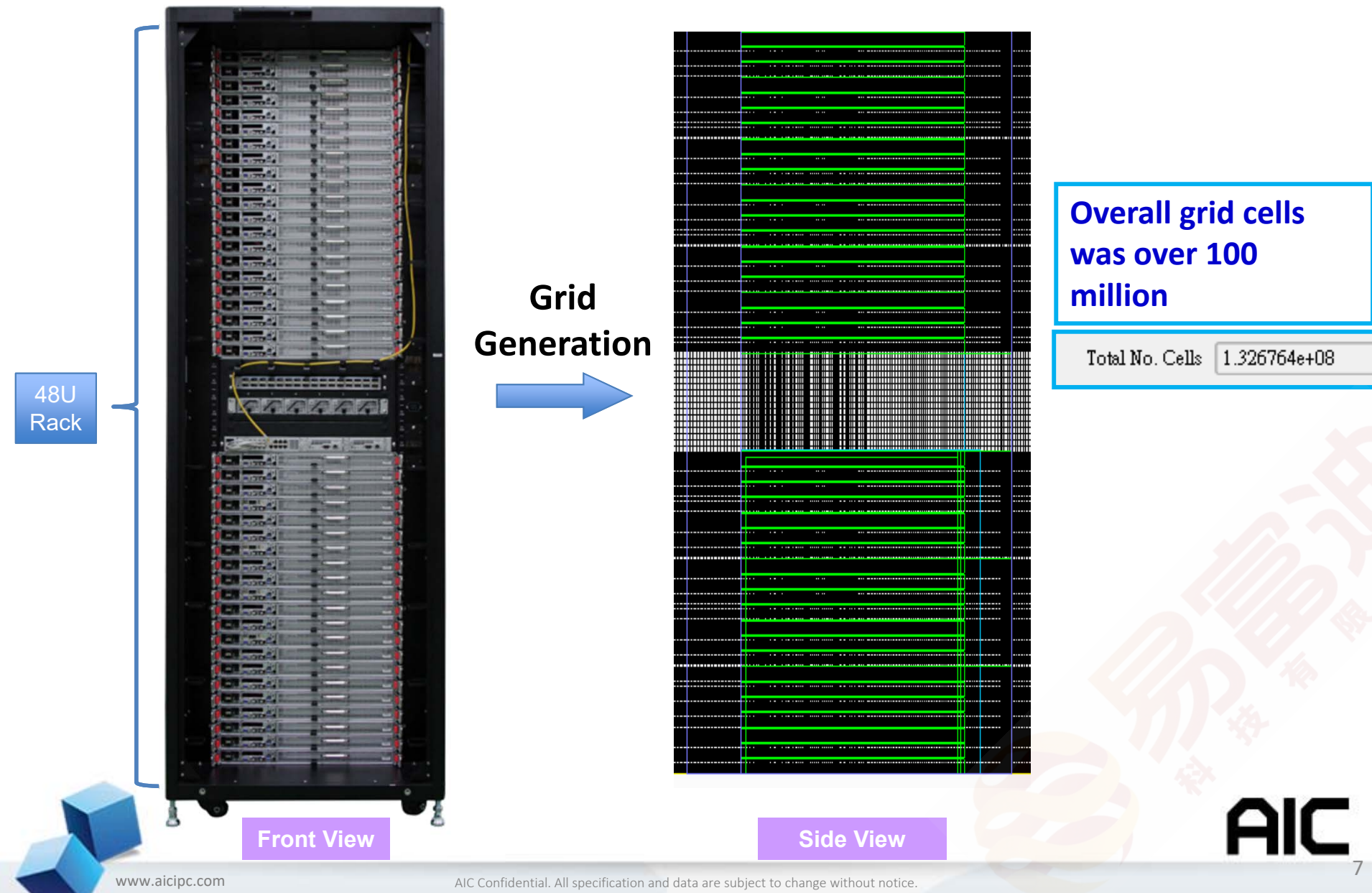
AIC

AIC Rack Thermal Simulation

Whole Rack Simulation Model



AIC Rack Thermal Simulation

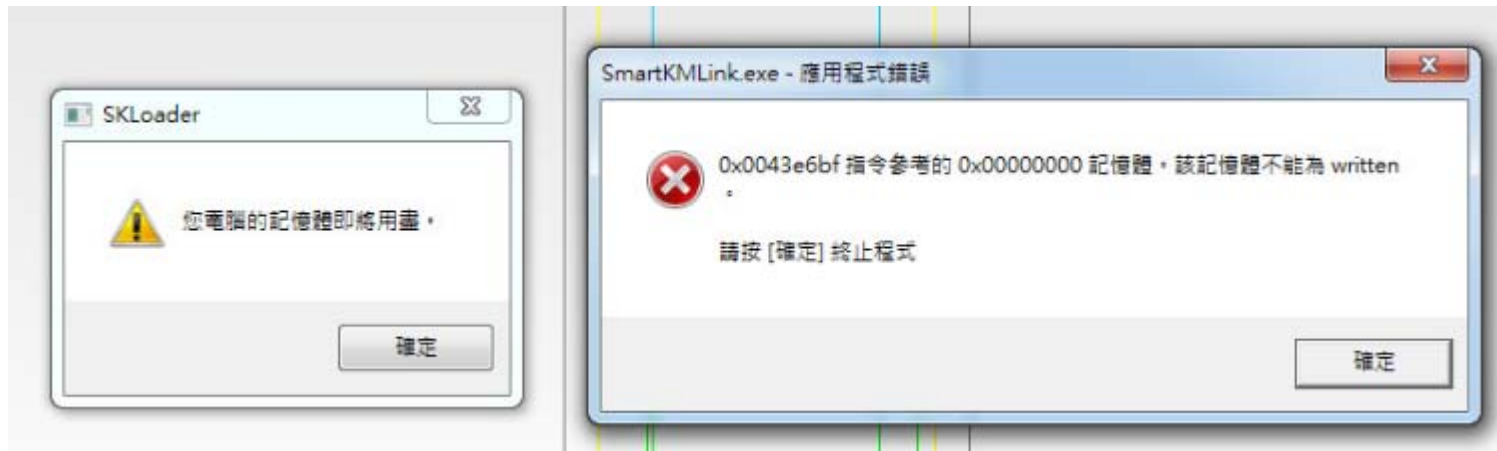


AIC Rack Thermal Simulation Result

After 3 days, I got the below message.



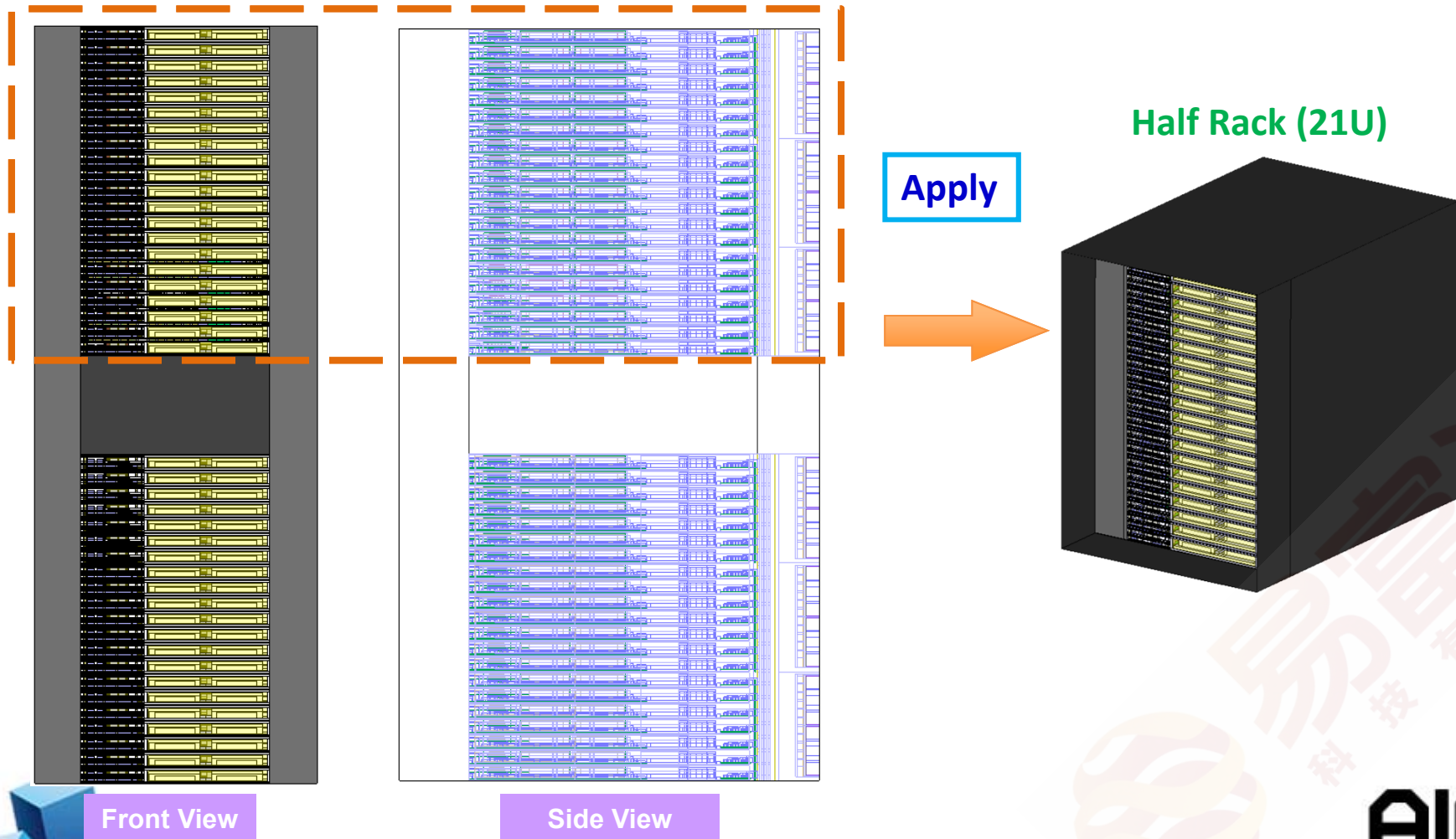
The memory is not enough.



The Solution to Thermal Simulation

Reduce the grid cells amount

→ Apply half Rack



Front View

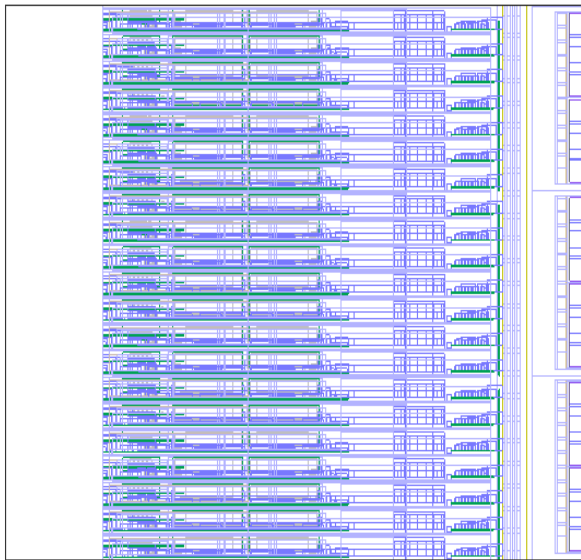
Side View

AIC

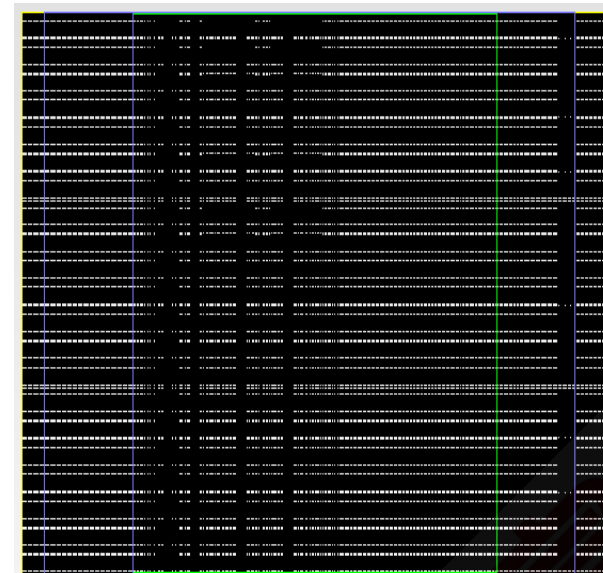
AIC Half Rack Thermal Simulation



Side View



Grid
Generation

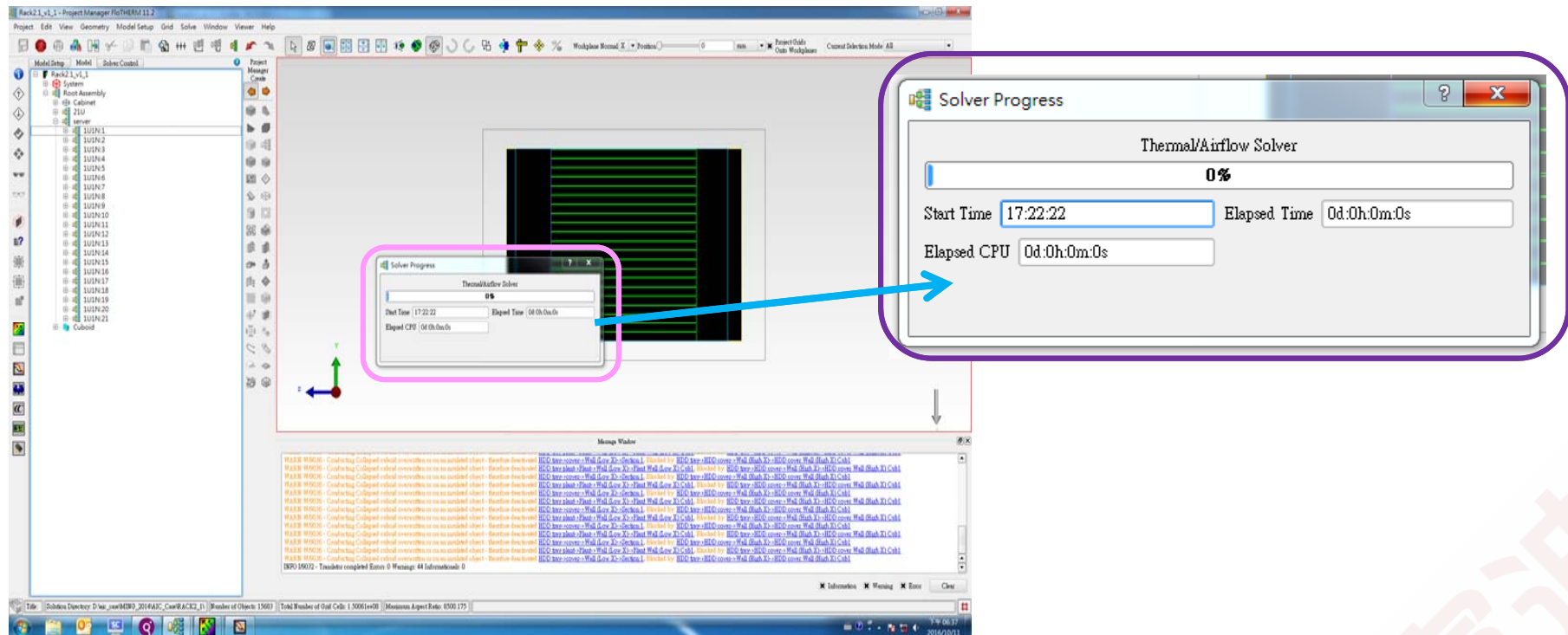


Total No. Cells 6.578412e+07

The grid cells are still a lot and more than 60 million.



AIC Half Rack Thermal Simulation Result



The thermal simulation can keep going.



AIC Half Rack Thermal Simulation Result

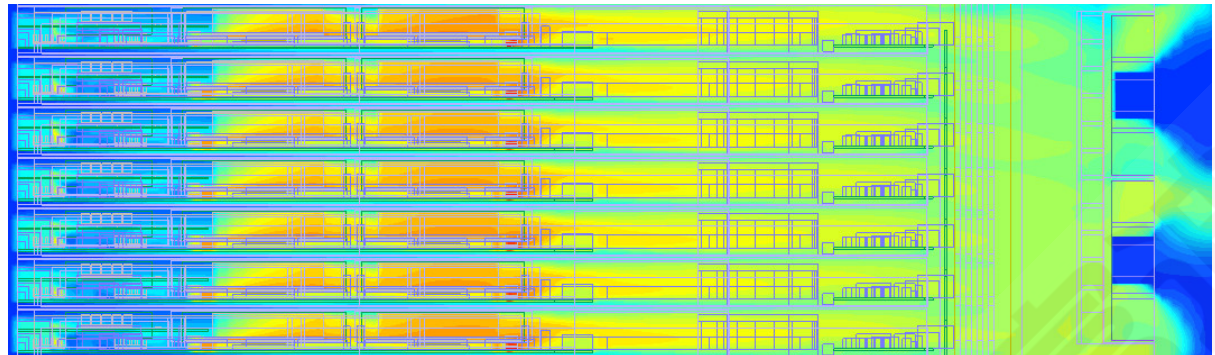
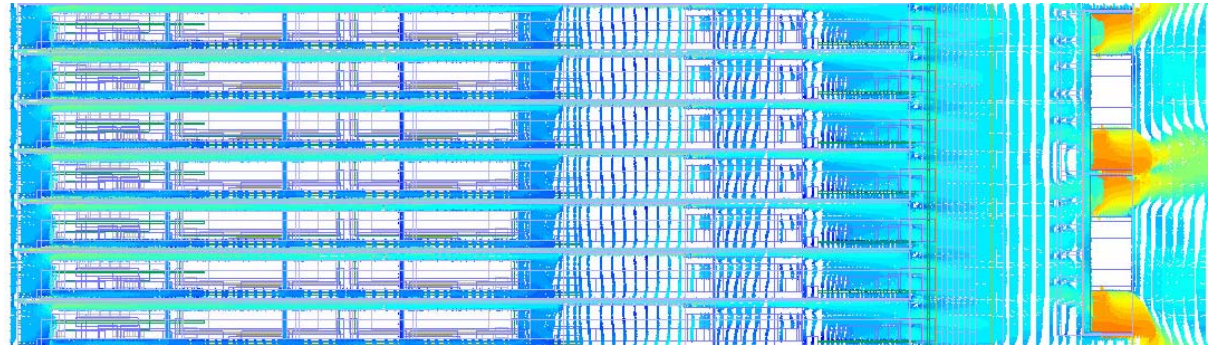
Front View



Simulation
Result



Side View

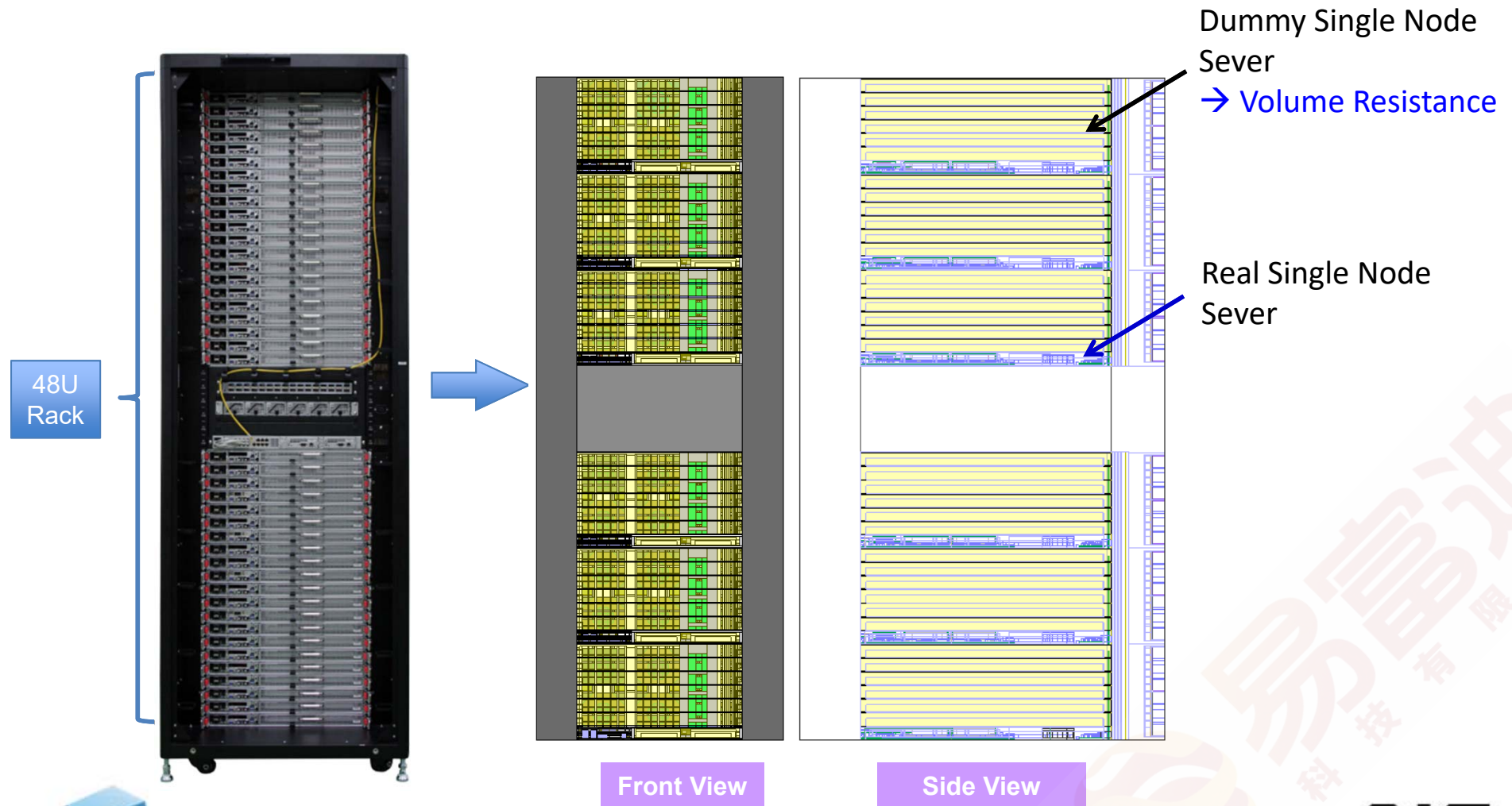


1. The thermal simulation had done and produced the simulation result..
2. The large grid cells made FloTHERM to spend lots of time performing.



Other Way to Reduce the Grid Cells

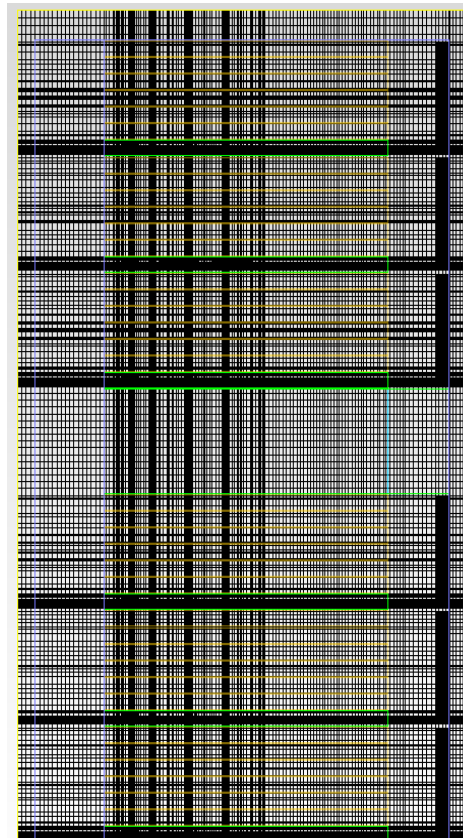
Apply volume resistance instead of real Sever model



Other Way to Reduce the Grid Cells



Grid
Generation
→



Total No. Cells 3.271042e+07

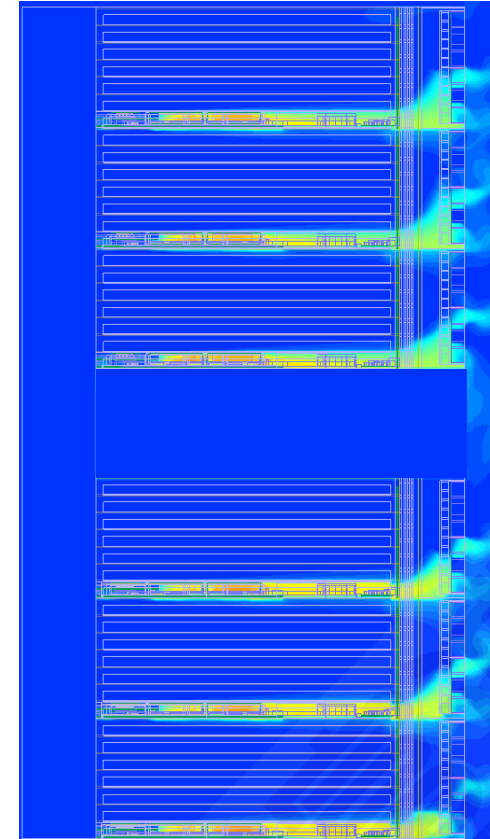
1. The grid cells was reduced to be about 30 million.
2. The simulation result is more easy and more capable to produce the result



Other Way to Reduce the Grid Cells



Simulation
Result



1. The thermal simulation was easily diversion.
2. The simulation result is acceptable.
3. The simulation performing time is acceptable.



More Request Detail of Mr. Mystery

1. Clearly know **Processors' temperature** in each node.
2. Clearly know **the temperature of Memory, BMC and PCH** in each node.
3. Clearly know **the chip temperatures of add-on card** in each node.
4. Clearly know **the temperature of HDDs in Sever Nodes or JBODs.**



Secret Behind of Mr. Mystery Request

Real Situation in Rack

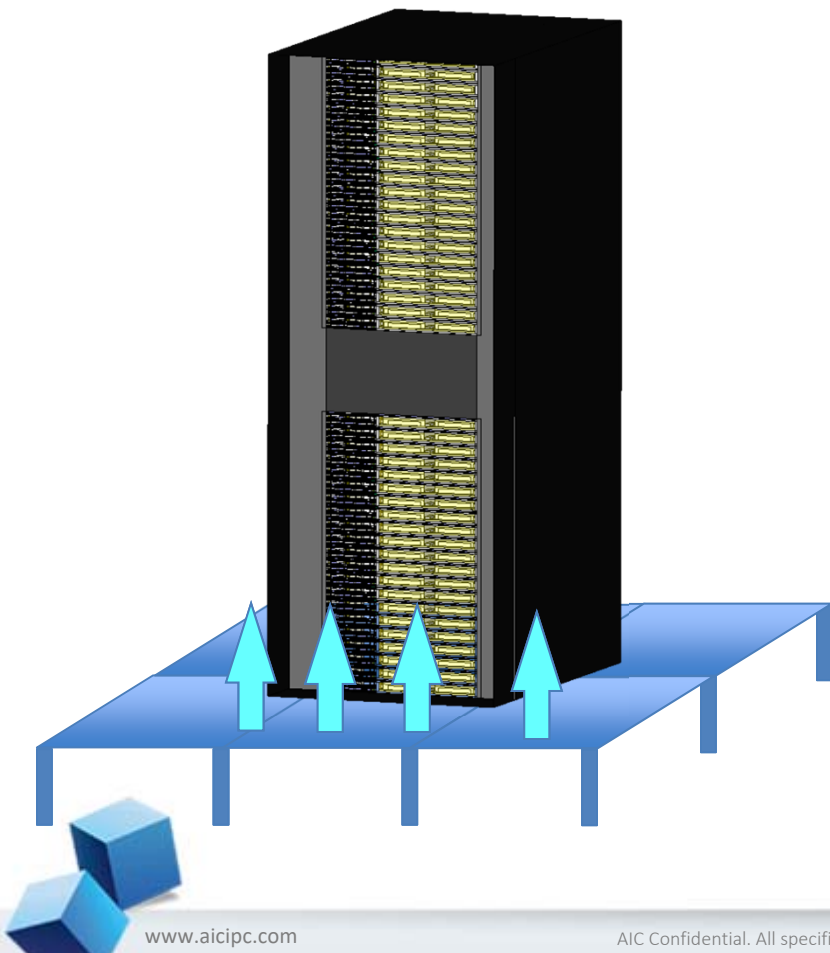
1. Are the inlet temperatures of each node same?
2. Is it separating the cold air zone and hot air zone in rack room?
3. The real situation of remove the server.



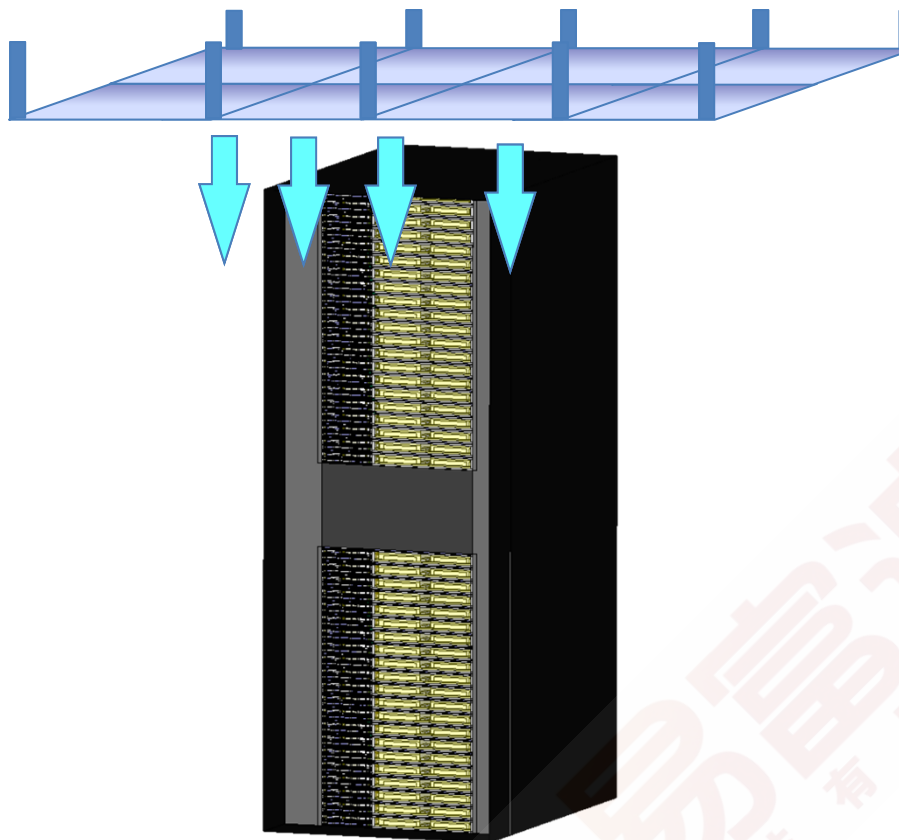
Rack Inlet Temperature

1. Are the inlet temperatures of each node same? → dT is 3C ~ 5C

Cold Air Flow Going Up



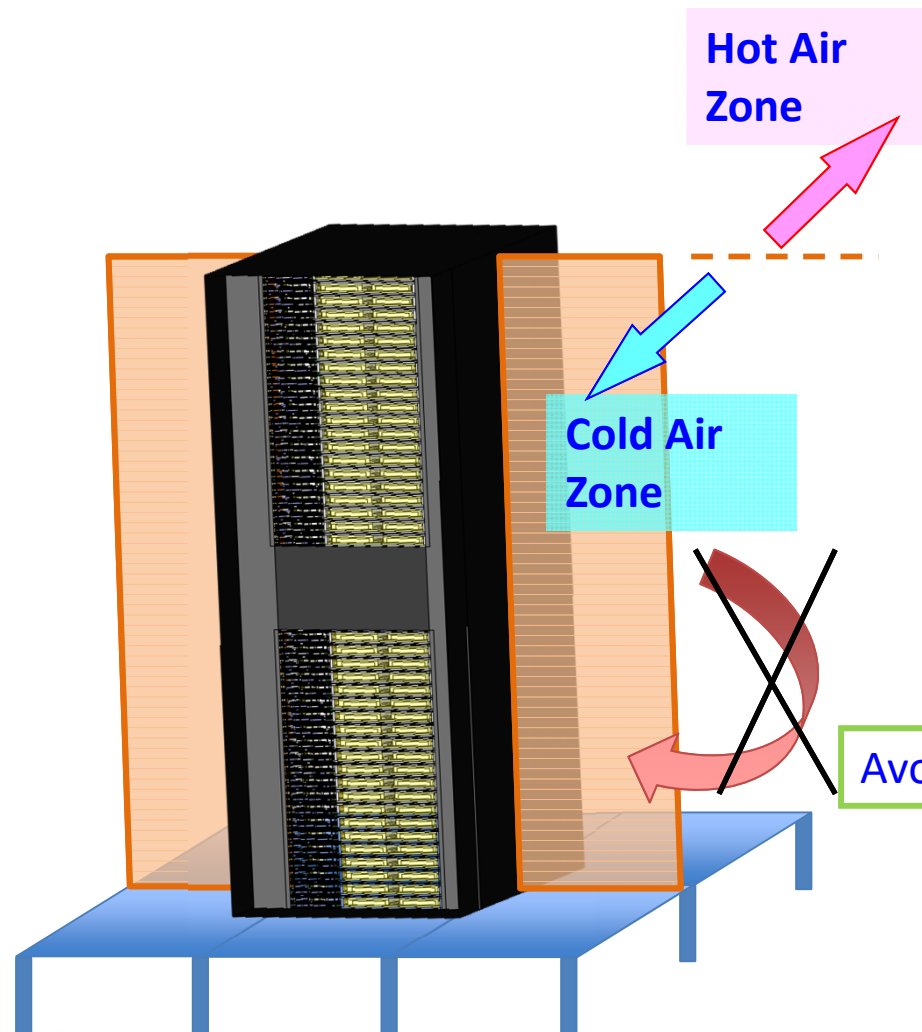
Cold Air Flow Going Down



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Rack Air Flow Condition

2. Is it separating the cold air zone and hot air zone?



Cold air zone and **Hot** air zone are **separated**

→ Make sure the hot air not to go back the front air inlet side.

Avoid the counter-flow of hot air.



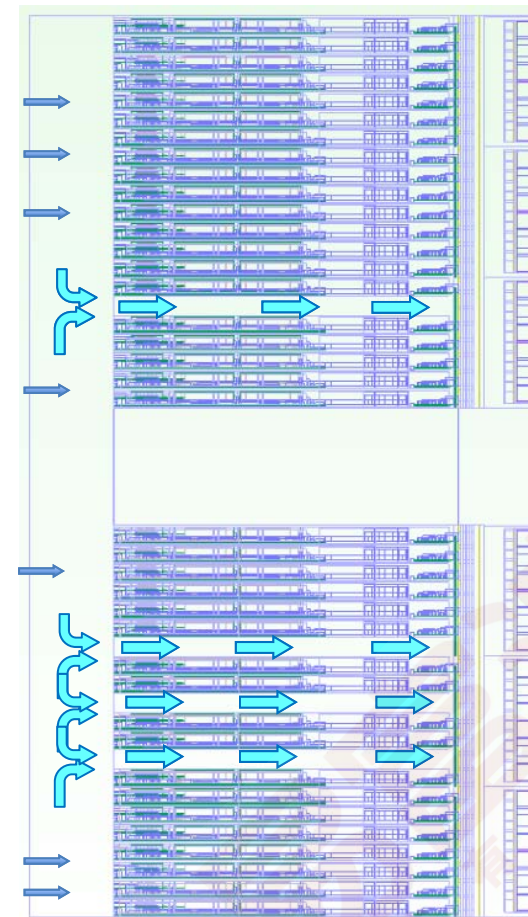
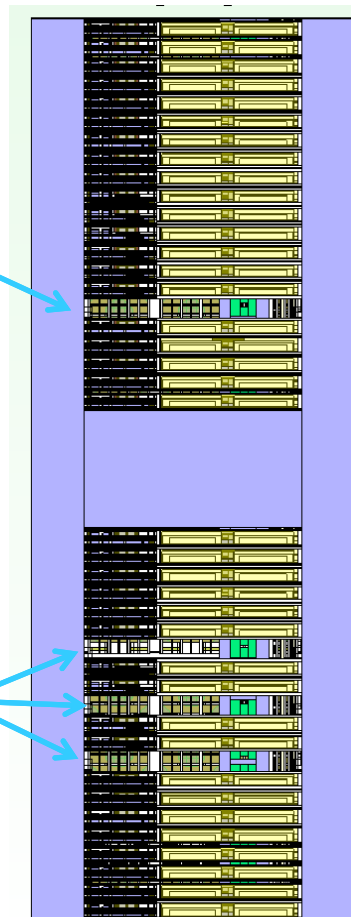
Remove Server from Rack

Lack of 1U or even more than 1U?



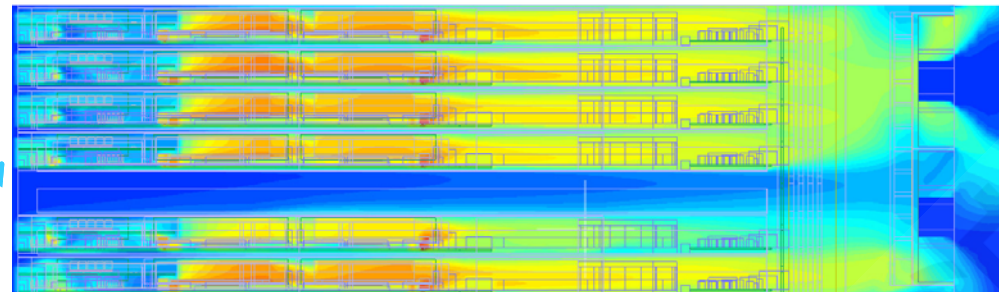
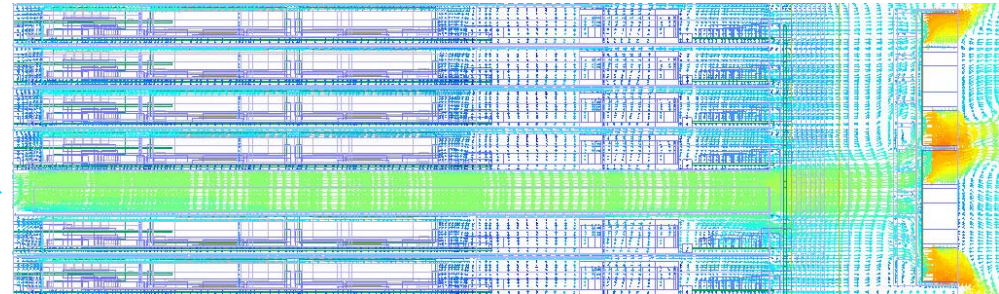
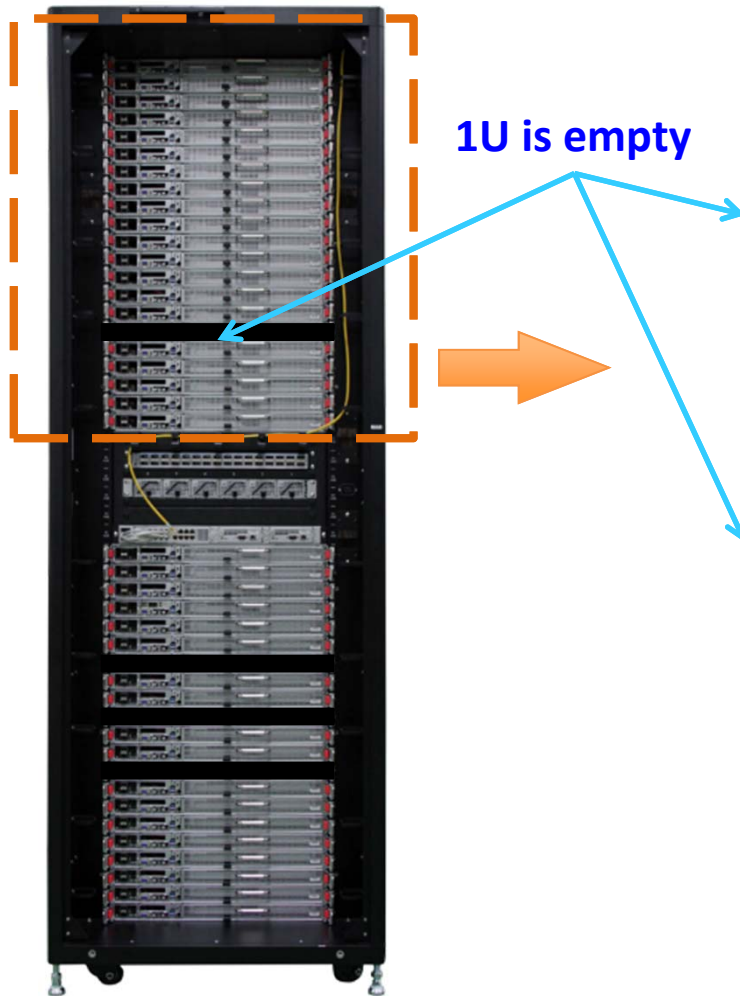
1U is empty

The empty Units
are empty



Remove Server from Rack

1U empty thermal simulation result



The CPU temperature was raising up
10~12C in nearest two Units
→ Needing a cover to block the
empty unit.



Summary

1. In Rack level thermal simulation, the key point is **Grid Cells**.
2. Building up the **suitable grid cells** simulation model can **save time** and **get the result**.
3. Performing **Rack** thermal simulation needs to consider more **detail** in **boundary conditions**.



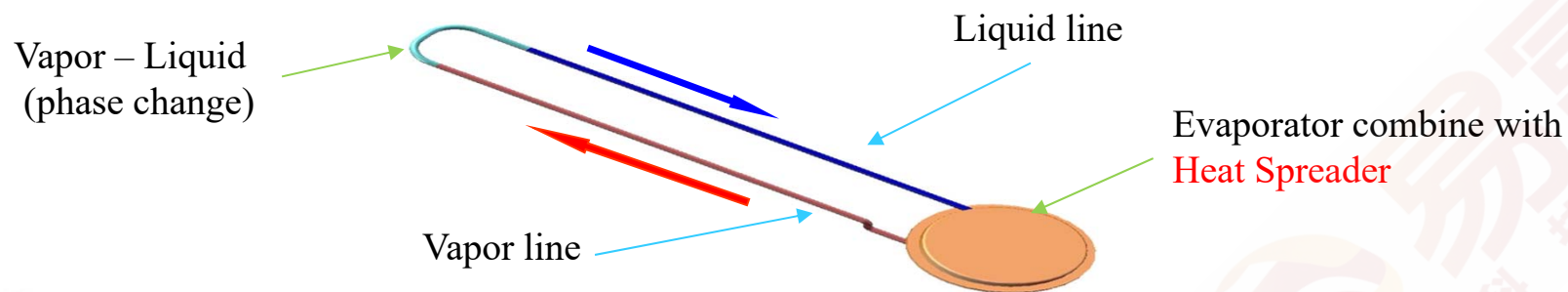
What is Next Step in Rack

1. Liquid Cooling.

- ◆ Rack level stand-alone cooling system.
- ◆ Combine with the Data Center cooling system

2. Loop Heat Pipe

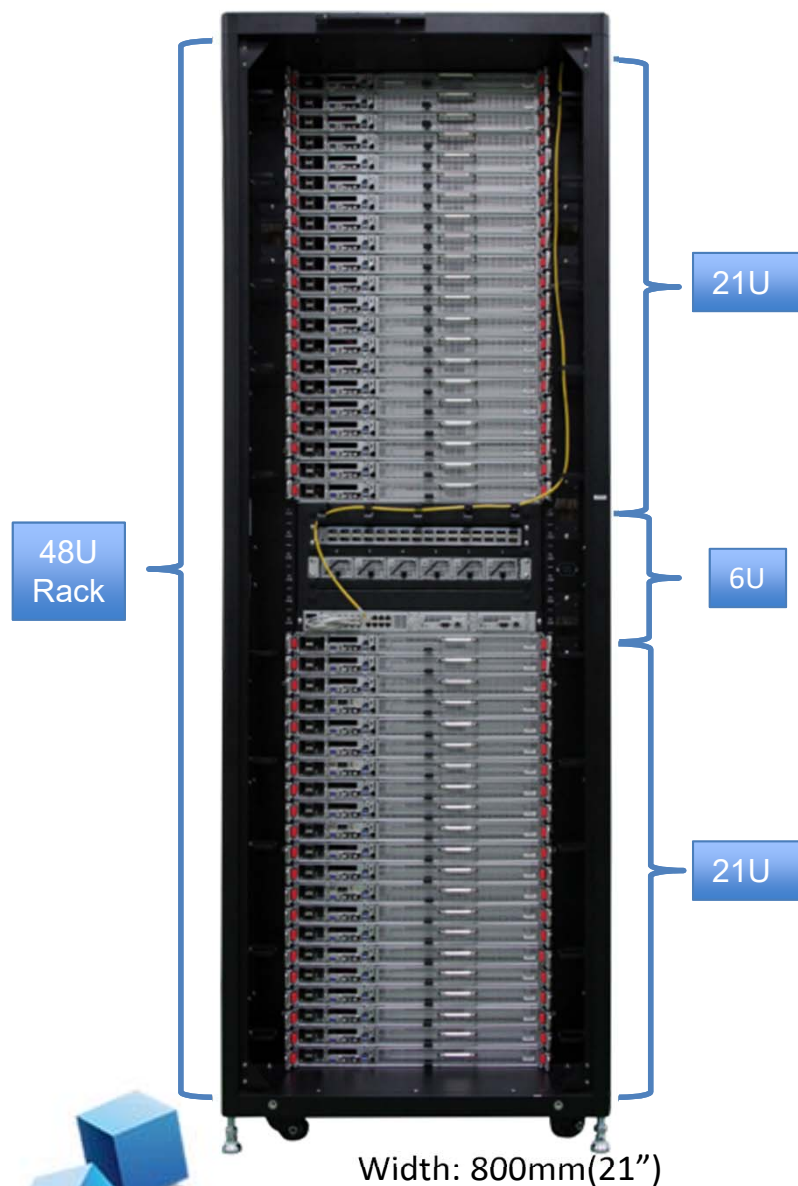
Hoject provided this new thermal solution Loop Heat Pipe.



Backup



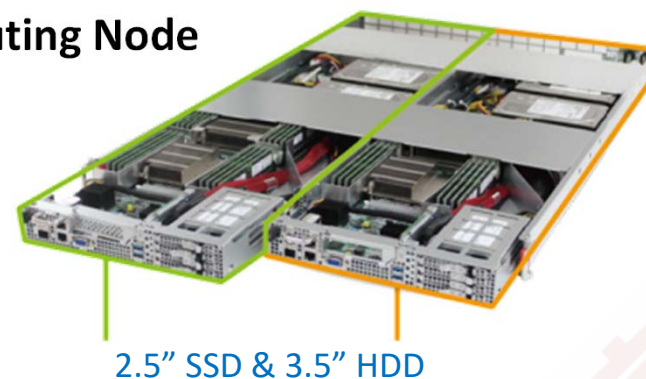
AIC Rack



Single Node



Computing Node



JBOD Node

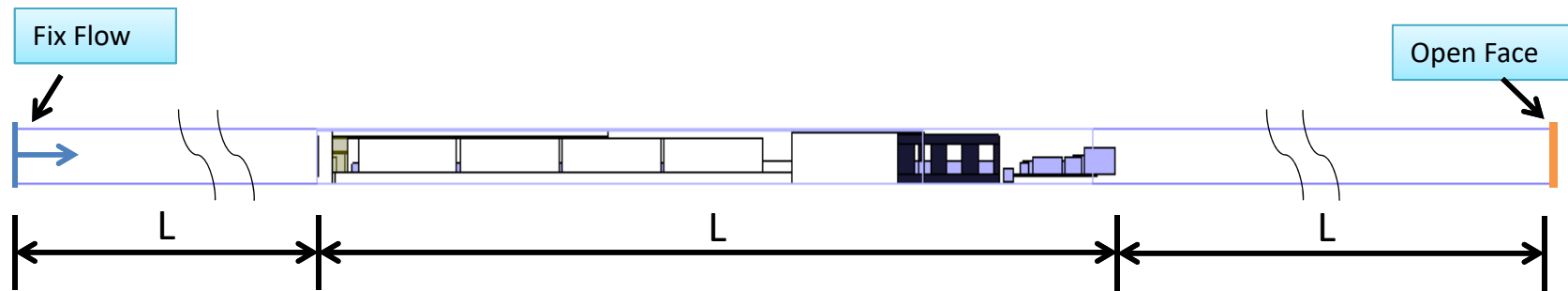


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Reduce Grid Amount

Applying Volume Resistance

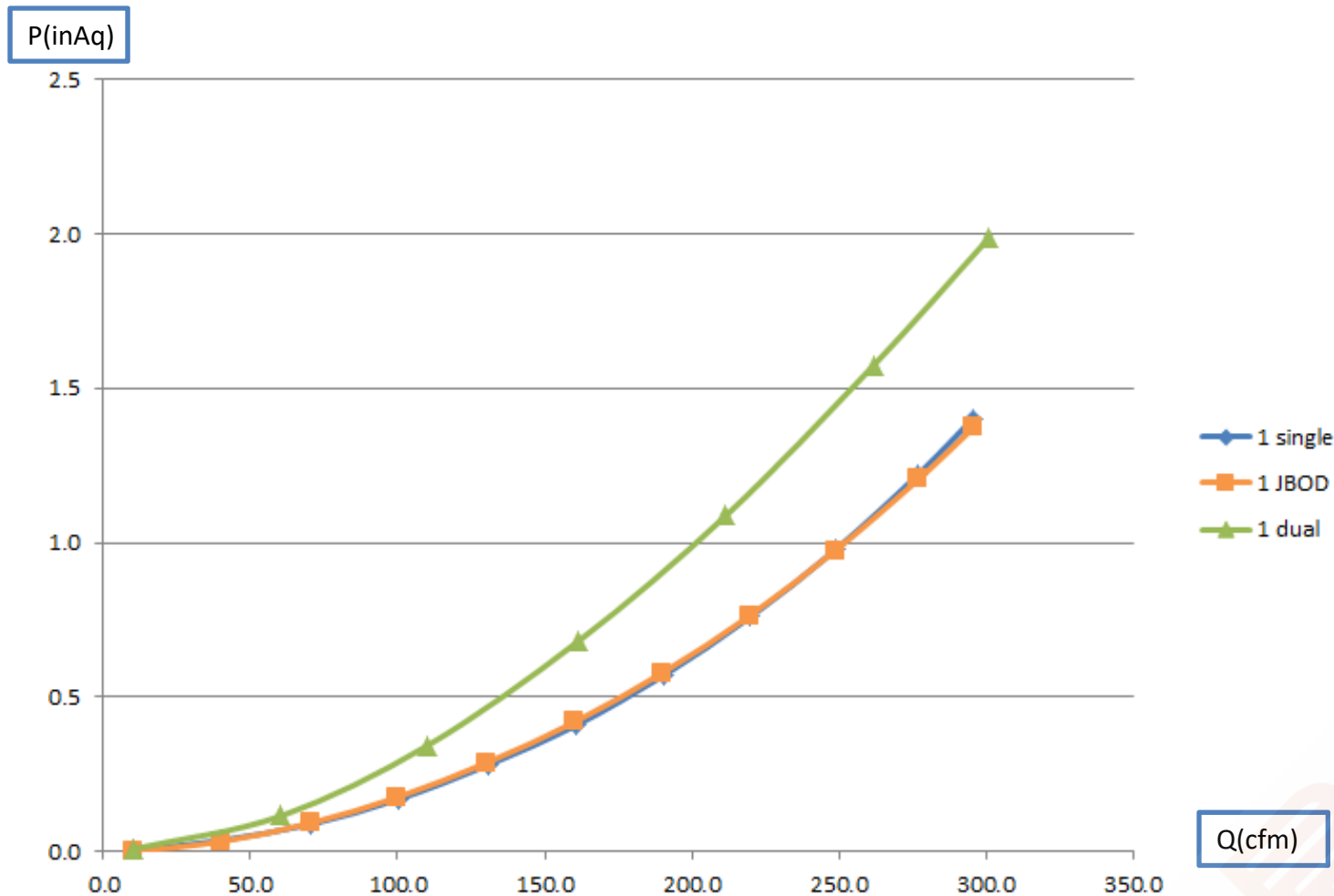
A. Digital Wind Tunnel



B. Doing Wind Tunnel Experiment



System Resistance



Impedance comparison: Dual node (1U) > Single node (1U)

Note: 2U30 JBOD is 2U node



Thank you

1. **Thank you. Mentor create and provide this amazing tool FloTHERM for our Thermal Engineers. Saving our time, tooling fee and recourse.**
2. **Tank you. EFD Corporation Jay and Bonnie always provide the strong technology support.**
3. **Thank you. AIC Thermal team members.**
4. **Thank you. Hoject provide the thermal solution and Loop Heat Pipe for thermal verification.**
5. **Thank you, everybody here.**



Thank you

